

A Report on MoU Signing Ceremony between
MITS, Deemed to be University & Sense Semiconductor and IT Solutions Pvt. Ltd
Organized by Department of Electronics and Communication Engineering
In Association with Industry Relation Cell MITS
Date: 24.02.2026



Report Submitted by: **G. Kumar, IRO-Industry Relations, MITS.**
Resource Person Details: **Mr. Sudheer Reddy, CEO, SSIT Pvt Ltd.**
Date & Venue: **24.02.2026, Board Room, MITS Madanapalle**
Time: **11:00 AM to 12:00 PM**
Mode of Conduct: **Offline**
Targeted Audience: **All Department students and staff**
Report Received on **02.03.2026.**

Objectives of the Program:

1. To establish a structured industry–academia collaboration between MITS and Sense Semiconductor & IT Solutions Pvt. Ltd. (SSIT) for enhancing technical learning and practical exposure for students.
2. To provide students with career awareness, skill development, and industry-relevant training through sessions, workshops, internships, and mentorship programs.
3. To enhance students' employability by enabling access to internship opportunities, placement guidance, and hands-on technical training in electronics, software, automation, healthcare, agriculture, and related domains.
4. To support faculty and student growth through research collaborations, consultancy projects, faculty development programs (FDPs), and participation in national and international technical events
5. To promote joint research and development activities that contribute to innovation and industry-oriented problem-solving
6. To strengthen institutional capabilities by establishing a consistent framework for collaboration, knowledge sharing, and skill enhancement aligned with current industry trends.
7. To create a sustainable and mutually beneficial partnership that supports long-term academic, professional, and technological development for both parties.

Report Summary:

Madanapalle Institute of Technology & Science (Deemed-to-be University), Madanapalle, and Sense Semiconductor & IT Solutions Pvt. Ltd. (SSIT), Mangalagiri, entered into a Memorandum of Understanding on **24th February 2026** to establish a structured industry–academia collaboration. The MoU was signed in the presence of **Dr. P. Ramanathan** – Principal, MITS, **Dr. Sanjay Kumar C. Goure** – Single Point of Contact (SPOC), HOD/ECE, **Prof. P. M. Balaji**, Assistant Director – Industry Relations; **Mr. Sudheer Reddy** – Chief Executive Officer, **N. Narendra Reddy** – Single Point of Contact (SPOC), SSIT Representative.

The MoU aims to strengthen academic–industry linkages by offering career awareness sessions, internship opportunities, placement guidance, training programs, workshops, seminars, and hackathons tailored to the needs of students from ECE, EEE, CSE, and other engineering departments. It also promotes joint research and development activities in areas such as automation, healthcare, agriculture, software, and EdTech, along with consultancy projects for students and faculty. The partnership includes support for Faculty Development Programs (FDPs) and encourages participation in research publications, grant applications, and competitions. Both institutions commit to maintaining confidentiality and respecting intellectual property rights, with SSIT retaining ownership of IP created under this MoU. The collaboration will be effective

for **three years** and is expected to significantly enhance student skills, faculty development, institutional research output, and overall industry readiness.

Program Outcomes:

- **PO1:** Students gain enhanced industry awareness through structured career awareness sessions conducted by SSIT, improving their understanding of career paths in electronics, IT, and related engineering domains.
- **PO2:** Improved employability and real-time exposure as students receive internship opportunities, placement guidance, and mentorship from industry professionals aligned with SSIT's technical requirements.
- **PO3:** Strengthened technical skills and problem-solving abilities through workshops, seminars, and hackathons focused on current industry developments and hands-on learning experiences.
- **PO4:** Enhanced research capabilities for faculty and students by participating in joint R&D projects in automation, healthcare, agriculture, software, EdTech, and related emerging areas.
- **PO5:** Increased academic productivity through support for publications, grant applications, consultancy work, and participation in national and international competitions.
- **PO6:** Faculty upskilling and professional development through Faculty Development Programs (FDPs) offered by SSIT on advanced technologies relevant to current academic and industry needs.
- **PO7:** Greater institutional–industry collaboration enabling long-term engagement, knowledge sharing, and mutual growth while ensuring consistent, transparent, and structured collaboration practices.

Conclusion:

The Memorandum of Understanding between Madanapalle Institute of Technology & Science (MITS) and Sense Semiconductor & IT Solutions Pvt. Ltd. (SSIT), signed on 24th February 2026, marks a significant step toward fostering a long-term, sustainable, and mutually beneficial partnership between academia and industry. This collaboration lays a structured foundation for enhancing student competencies through internships, hands-on training, career awareness programs, and mentorship, while also empowering faculty through continuous professional development and participation in research and consultancy activities.

By integrating academic strength with industry expertise, the MoU aims to cultivate innovation across interdisciplinary domains such as automation, healthcare, agriculture, software, and EdTech. Both institutions have committed to maintaining confidentiality, respecting intellectual property, and working collaboratively in good faith to achieve the defined objectives. Effective immediately, and valid for three years, this MoU reinforces the shared vision of improving academic excellence, industry readiness, and research productivity, ultimately contributing to the holistic development of students, faculty, and institutional capabilities.